

Andrew N Lemmon

List of Publications by Year in descending order

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45
papers

607
citations

933447

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all docs

45
docs citations

45
times ranked

493
citing authors

#	ARTICLE	IF	CITATIONS
1	Design of an Absorptive High-Power PIN Diode Switch for an Ultra-Wideband Radar. IEEE Journal of Microwaves, 2022, 2, 286-296.	6.5	3
2	Improved Methodology for Parasitic Analysis of High-Performance Silicon Carbide Power Modules. IEEE Transactions on Power Electronics, 2022, 37, 12415-12425.	7.9	3
3	Improved Methodology for Estimating Switching Losses of Wide Band-Gap Semiconductors Using Gaussian Curve Fitting. , 2022, , .		0
4	Optimization Algorithms for Dynamic Tuning of Wide Bandgap Semiconductor Device Models. , 2021, , .		4
5	Comprehensive Characterization of MOSFET Intrinsic Capacitances. , 2021, , .		7
6	EMI Evaluation of a SiC MOSFET Module with Organic DBC Substrate. , 2021, , .		8
7	Impact of Output Terminations on Conducted Emissions Evaluation of Interface Converters. , 2021, , .		0
8	Computational Efficiency Analysis of SiC MOSFET Models in SPICE: Dynamic Behavior. IEEE Open Journal of Power Electronics, 2021, 2, 106-123.	5.7	14
9	Analysis and Cancellation of Leakage Current Through Power Module Baseplate Capacitance. IEEE Transactions on Power Electronics, 2020, 35, 4678-4688.	7.9	19
10	Multibranch Inductance Extraction Procedure for Multichip Power Modules. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2020, 8, 272-285.	5.4	7
11	Modeling of ZVS Transitions for Efficiency Optimization of the Phase-Shifted Full-Bridge Topology. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2020, 8, 529-544.	5.4	11
12	Estimation, Minimization, and Validation of Commutation Loop Inductance for a 135-kW SiC EV Traction Inverter. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2020, 8, 286-297.	5.4	42
13	Modeling and Validation of Common-Mode Emissions in Wide Bandgap-Based Converter Structures. IEEE Transactions on Power Electronics, 2020, 35, 8034-8049.	7.9	26
14	Modeling and Validation of Conducted Emissions Trends in Medium-Voltage Power Electronic Systems. , 2020, , .		4
15	Measurement-Based Modeling of Power Module Parasitics with Increased Accuracy. , 2020, , .		6
16	Experimental Validation of CT-Snubber for Multichip SiC MOSFET Power Module. , 2020, , .		0
17	Computational Efficiency Analysis of SiC MOSFET Models in SPICE: Static Behavior. IEEE Open Journal of Power Electronics, 2020, 1, 499-512.	5.7	16
18	An Automated Model Tuning Procedure for Optimizing Prediction of Transient and Dispersive Behavior in Wide Bandgap Semiconductor FETs. IEEE Transactions on Power Electronics, 2020, 35, 12252-12263.	7.9	4

#	ARTICLE	IF	CITATIONS
19	Improved Methodology for Parasitic Characterization of High-Performance Power Modules. IEEE Transactions on Power Electronics, 2020, 35, 13400-13408.	7.9	10
20	Design and Characterization of a Neutral-Point-Clamped Inverter Using Medium-Voltage Silicon Carbide Power Modules. , 2020, , .		8
21	Modeling and Validation of Medium Voltage SiC Power Modules. , 2020, , .		11
22	Comparison of Medium-Voltage Oscilloscope Probes for Evaluating Silicon-Carbide Multi-Chip Power Modules. , 2020, , .		2
23	Modeling and Validation of Fixture-Induced Error for Impedance Measurements. IEEE Transactions on Instrumentation and Measurement, 2019, 68, 129-137.	4.7	9
24	Bus Snubber Optimization for Multi-Chip Power Modules using SPICE Simulations. , 2019, , .		0
25	Cancellation of Leakage Currents through Power Module Baseplate Capacitance. , 2019, , .		7
26	Comparison of Methods for Switching Loss Estimation in WBG Systems. , 2019, , .		3
27	Utilization of Power Module Baseplate Capacitance for Common-Mode EMI Filter Reduction. , 2019, , .		4
28	A SiC-based isolated DC/DC converter for high density data center applications. , 2018, , .		4
29	An automated SPICE modeling procedure utilizing static and dynamic characterization of power FETs. , 2018, , .		5
30	Methodology for Characterization of Common-Mode Conducted Electromagnetic Emissions in Wide-Bandgap Converters for Ungrounded Shipboard Applications. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2018, 6, 300-314.	5.4	44
31	Application-focused modeling procedure for 1.2kV SiC MOSFET's. , 2017, , .		5
32	Technique for embedding current measurement and ringing suppression within multichip modules. , 2017, , .		2
33	Characterization and Modeling of 10-kV Silicon Carbide Modules for Naval Applications. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2017, 5, 309-322.	5.4	32
34	Effects of parasitic inductance on performance of 600-V GaN devices. , 2017, , .		7
35	Common-mode/differential-mode interactions in asymmetric converter structures. , 2017, , .		12
36	Multi-branch inductance extraction procedure for multi-chip power modules. , 2016, , .		7

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37	Comprehensive Characterization of 10-kV Silicon Carbide Half-Bridge Modules. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2016, 4, 1462-1473.	5.4	26
38	Control and characterization of electromagnetic emissions in wide band gap based converter modules for ungrounded grid-forming applications. , 2016, , .		15
39	Methodology for the volume minimization in non-isolated SiC based PV inverters. , 2015, , .		6
40	Parasitic extraction procedure for silicon carbide power modules. , 2015, , .		41
41	Gate drive development and empirical analysis of 10 kV SiC MOSFET modules. , 2015, , .		4
42	Behavioral modeling for stability in multi-chip power modules. , 2015, , .		11
43	Fast, configurable over-current protection for high-power modules. , 2015, , .		7
44	Instability in Half-Bridge Circuits Switched With Wide Band-Gap Transistors. IEEE Transactions on Power Electronics, 2014, 29, 2380-2392.	7.9	131
45	ImagePAD, a novel counting application for the Apple iPad [®] , used to quantify axons in the Mouse Optic Nerve. Experimental Eye Research, 2014, 128, 102-108.	2.6	20